	Material Comp © Copyright 2005. I International and Par	osition Dec PC, Bannockb n-American co	claration ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration	ation on a contract of the second sec	of the substances mpasses all lowe	s within the er level ma	e manufactur terials for wi	er listed i hich the r	item. Note nanufactu	e: if the item is an irer has engineerir	assembly with lowe g responsibility.
1752-21.1					Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier	r Information														
Company name* Comp				ompany unique ID			Unique ID Authority					Response Date*			
onsemi												2025-06-01			
Contact N	lame	Title - Contact				Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
Product-H	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing Site			ring Site	Weight*		UOM	Unit Type	
	1N4001						2025-06-01						250.82	mg	Each
Manufa	cturing Proccess Informa	tion										1			
	Terminal Plating / Grid Array Material 7			Ferminal Base Alloy J-STD-020 MSL			Peak Process Body Temperature Max Time at P			ime at Peak	k Temperature Number of Reflow Cycles				
			CU Alloy				C 30				seconds 3				
Comments	8														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.18	mg	Supplier	Silicon (Si)	7440-21-3		0.18	mg
Die Attach Solder	7.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1995	mg
			А	Lead (Pb)	7439-92-1	7a	7.3815	mg
			Supplier	Tin (Sn)	7440-31-5		0.399	mg
Lead Frame	125.08	mg	Supplier	Copper (Cu)	7440-50-8		125.08	mg
Mold Compound-Black	116.8	mg		Metal Hydroxide	proprietary data		5.84	mg
			Supplier	Carbon Black (C)	1333-86-4		1.168	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		87.6	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		11.68	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.512	mg
Plating	0.78	mg	Supplier	Tin (Sn)	7440-31-5		0.78	mg